UCC28250 1/8th Brick Reference Design
40-75V input, 12V/15A Output

Test Report
This document refers to test results for a standard Eighth Brick reference design featuring Texas Instruments parts.
Design criteria: Vout=12v @ 15 Amps, Vin range=40-75 Volts DC. Secondary side control.

TI content: UCC28250 PWM controller, UCC27201 High and Low side Mosfet Driver, UCC27324 Low side Mosfet Driver, UCC25230 Bias PWM Contoller, ISO7220 Digital Isolator, OPA365 High Performance Op Amp, TPS76201 Linear regulator, LM4041 Shunt Regulator

![Graph showing efficiency vs. current]
UCC28250_EIGHTHBRICK  Power Dissipation

UCC28250_EIGHTHBRICK  Line Regulation
Thermal images of top side.

Vin=40V Iout=0A, Hot spot is Transformer core. 0 cfm
Vin=60V Iout=0A, Hot spot is Transformer core. 0 cfm

Vin=40V Iout=15A, Hot spot is PCB near primary mosfets. 0 cfm
Yellow(channel 1)=Vin, Blue(channel 2)=Vout, Pink(channel 3)=primary bias, Green(channel 4)=secondary bias; \[ \text{Vin}=40\text{V} \quad \text{Iout}=0\text{A} \quad \text{External capacitance}=150\text{uf} \]
Yellow(channel 1)=Vin, Blue(channel 2)=Vout, Pink(channel 3)=primary bias, Green(channel 4)=secondary bias; Vin=40V Iout= 5A External capacitance=150uf

Yellow(channel 1)=Vin, Blue(channel 2)=Vout, Pink(channel 3)=primary bias, Green(channel 4)=secondary bias; Vin=40V Iout= 10A External capacitance=150uf
Yellow (channel 1) = Vin, Blue (channel 2) = Vout, Pink (channel 3) = primary bias, Green (channel 4) = secondary bias;  
 Vin = 40 V, Iout = 15 A, External capacitance = 150 uf

Yellow (channel 1) = Vin, Blue (channel 2) = Vout, Pink (channel 3) = primary bias, Green (channel
4) secondary bias;  \textbf{Vin=48V Iout= 0A} External capacitance=150uf

Yellow(channel 1)=Vin, Blue(channel 2)=Vout, Pink(channel 3)=primary bias, Green(channel 4)=secondary bias;  \textbf{Vin=48V Iout= 5A} External capacitance=150uf
Yellow (channel 1) = Vin, Blue (channel 2) = Vout, Pink (channel 3) = primary bias, Green (channel 4) = secondary bias; Vin = 48V, Iout = 10A, External capacitance = 150uf

Yellow (channel 1) = Vin, Blue (channel 2) = Vout, Pink (channel 3) = primary bias, Green (channel 4) = secondary bias; Vin = 48V, Iout = 15A, External capacitance = 150uf
Yellow(channel 1) = Vin, Blue(channel 2) = Vout, Pink(channel 3) = primary bias, Green(channel 4) = secondary bias; Vin = 60V Iout = 0A External capacitance = 150uf
Vin=60V  Iout= 5A  External capacitance=150uf

Yellow(channel 1)=Vin, Blue(channel 2)=Vout, Pink(channel 3)=primary bias, Green(channel 4)=secondary bias;  Vin=60V  Iout= 10A  External capacitance=150uf
Yellow(channel 1) = Vin, Blue(channel 2) = Vout, Pink(channel 3) = primary bias, Green(channel 4) = secondary bias; Vin=60V Iout=15A External capacitance=150uf

Enable vs Vout
Yellow(channel 1) = Vin, Blue(channel 2) = Vout; Vin = 40V, Iout = 5A, External capacitance = 150uf

Yellow(channel 1) = Vin, Blue(channel 2) = Vout; Vin = 48V, Iout = 5A, External capacitance = 150uf
Yellow(channel 1)=Vin, Blue(channel 2)=Vout; Vin=60V Iout=5A External capacitance=150uf

Vout with 6v Prebias

Yellow(channel 1)=Vout; Vin=48V Iout=0A External capacitance=150uf
Yellow(channel 1)=Vout; Vin=48V Iout=0A External capacitance=150uf

Output Ripple
Vin=48V Iout=0A External capacitance=150uf

Vin=48V Iout=15A External capacitance=150uf

Vin Step change 40v to 60v
Yellow(channel 1)=Vin, Blue(channel 2)=Vout; Iout=5A 400mv deviation External capacitance=150uf

Iout Load Step change 5A to 10A and 10A to 5A

Vout response with 50% step change in load. External capacitance=150uf
Vin=48v Iout=10A

External capacitance=150uf

Yellow(channel 1)=Transformer Primary Voltage, Blue(channel 2)=Vout; External capacitance=150uf
The board was externally heated in the area of the sense thermistor for the Over temp detection circuit. The waveforms show the hiccup delay before switching resumes and the output returning with no overshoot after the temperature is reduced.

Yellow (channel 1) = Transformer Primary Voltage External capacitance = 150uf

Expanded view of the primary voltage of the power transformer showing no asymmetry during the hiccup recovery period.

Over Current
Yellow(channel 1)=Transformer Primary Voltage, Blue(channel 2)=Vout; Iout=20A External capacitance=150uf

Yellow(channel 1)=Transformer Primary Voltage, Blue(channel 2)=Vout; Iout=20A External capacitance=150uf Expanded view of the primary voltage of the power transformer showing no asymmetry during the hiccup recovery period.
Yellow(channel 1) = Vout, Blue(channel 2) = Transformer Primary Voltage; Iout = 20A
External capacitance = 150uf. Converter in Hiccup mode during Over current condition.
Featuring very low power dissipation when exhibiting an over current fault.
Summary

The intent of this design was to highlight some of features of the UCC28250 PWM controller, such as a programmable hiccup timer for fault conditions, prebias startup capability, adjustable timing on gate drive signals for synchronous rectifiers and the ability to have feed forward compensation with a secondary side controller.

The secondary side bias power and startup is provided by Texas Instruments UCC25230 bias supply controller with built in power devices. This device is capable of 75v operation with 100v surges and up to 250mA of peak current. By utilizing a forward flyback topology allows for simpler magnetic design for the bias supply to provide controller power for both primary and secondary side circuitry.

As can be observed by the previous data, a high efficiency eighth brick reference design can be achieved using Texas Instruments comprehensive line of power solutions.

Notes:
All data was taken at room ambient approximately 25 degrees C, minimal airflow of 200LFM unless otherwise noted. No data was taken at extreme cold or elevated temperatures. The design would need to be optimized for specific applications and specifications.

Over current sensing is done by amplifying a differential voltage across an embedded copper trace on the secondary side.

This reference design does not have any compensation for temperature or input voltage changes for the current sensing method used. It would need to be modified for an end user application to allow for input voltage range, printed circuit board materials and temperature variations.
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